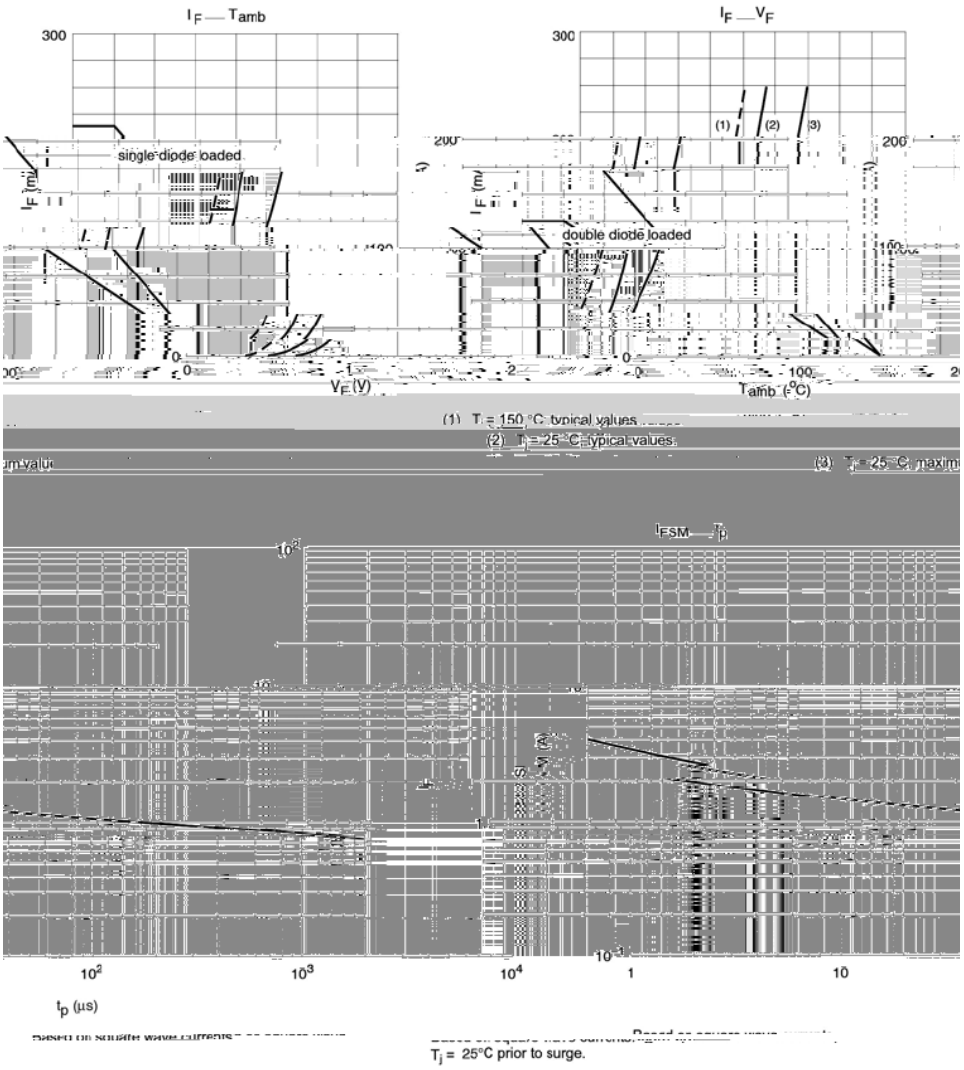
/ Absolute Maximum Ratings(Ta=25)

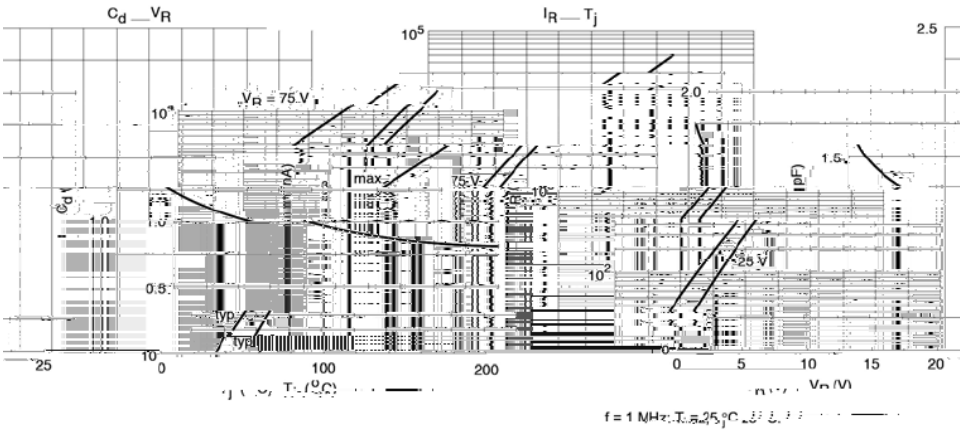
Parameter	Symbol	Rating	Unit
Repetitive Reverse Voltage	V_{RRM}	85	V
Continuous Reverse Voltage	V_R	75	V
Average Rectified Forward Current	$I_{F(single\ diode\ loaded)}$	215	mA
	$I_{F(double\ diode\ loaded)}$	125	mA
Repetitive Peak Forward Current	I_{FRM}	450	mA
Non-repetitive Peak Forward Surge Current	$I_{FSM(1)(t=1\mu S)}$	4.0	A
	$I_{FSM(2)(t=1mS)}$	1.0	A
	$I_{FSM(3)(t=1S)}$	0.5	A
Power Dissipation	P_{tot}	250	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

/ Electrical Characteristics(Ta=25)

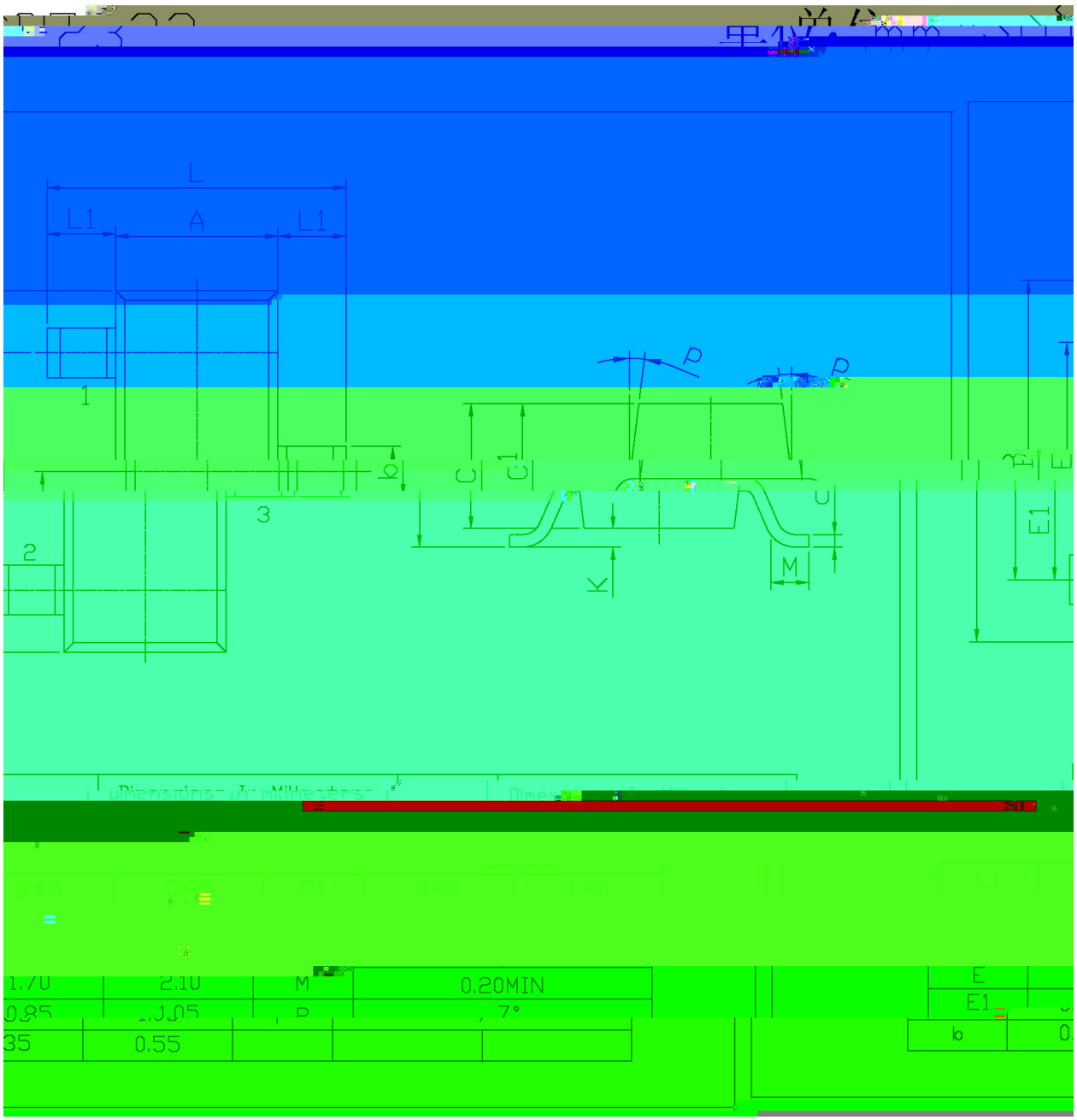
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	V_F	I_F=1.0mA			715	mV
		I_F=10mA			855	mV
		I_F=50mA			1.0	V
		I_F=150mA			1.25	V
Instantaneous Reverse Current	I_R	V_R=25V			30	nA
		V_R=75V			1.0	μA
		V_R=25V T_A=150			30	μA
		V_R=75V T_A=150			50	μA
Total Capacitance	C_T	V_R=0 f=1.0MHz			2.0	pF
Reverse Recovery Time	t_{rr}	I_F=I_R=10mA I_{RR}=1.0mA R_L=100Ω			4.0	ns
Forward recovery voltage	V_{ft}	I_F=10mA t_r=20ns			1.75	V

/ Electrical Characteristic Curve

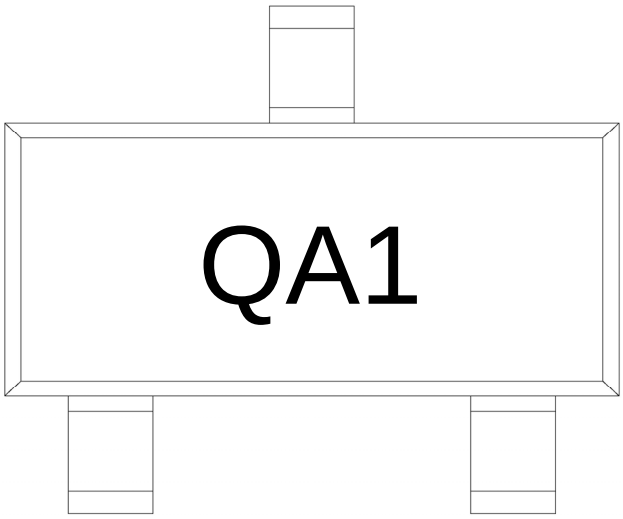




/ Package Dimensions



/ Marking Instructions



Note:

Q: Automobile halogen-free product Code

A1: Product Type

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:

1	150 200 60 120sec;	1.Preheating:150~200 , Time:60~120sec.
2	255 5 5 0.5sec;	2.Peak Temp.:255 5 , Duration:5 0.5sec.
3	2 10 /sec.	3.Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5 10 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL